

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/756,971  
Filing Date ..... January 9, 2001  
Inventor ..... Salman Akram  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2827  
Examiner ..... David A. Zarneke  
Attorney's Docket No. .... MI22-1572  
Title: Methods of Forming Board-On-Chip Packages

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

References -See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449. No admission is made regarding whether the submitted references are prior art.

Citation of the referenced art is respectfully requested.

The Commissioner is hereby authorized to charge any fees under 37 C.F.R. 1.16 and 1.17 which may be required by this paper to Deposit Account No. 23-0925.

08/22/2003 JMCILLA 00000007 230925 09756971

01 FC:1806 1806 0

Respectfully submitted,

Dated: 7-7-03By: 

D. Brent Kenady  
Reg. No. 40,045

S:\MI22\1572\12.wpd A270212261101N

1

Received from &lt;5098383424&gt; at 7/7/03 12:48:48 PM [Eastern Daylight Time]